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# Baseline Proposal

## Cable assembly, Host, MTF, and Channel Insertion Loss

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# Purpose

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- **Baseline proposal for cable assembly, Host, MTF, and Channel Insertion loss budgets**

# Contributors

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- **Scott Sommers, Tom Plalkert, Alex Haser – Molex**
- **Jane Lim, Upen Reddy – Cisco**
- **Samuel Kocsis, Greg Mcsorley - Amphenol**
- **Nathan Tracy – TE**
- **Rich Mellitz - Samtec**

# Supporters

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- **Scott Sommers, Tom Plalkert, Alex Haser – Molex**
- **Jane Lim, Pirooz Tooyserkani – Cisco**
- **Samuel Kocsis, Greg Mcsorley – Amphenol**
- **Nathan Tracy – TE**
- **Rick Rabinovich – Keysight**

# Supporting presentations

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- **Cable assembly - palkert\_3ck\_01a\_0519.pdf**
- **Host - lim\_3ck\_CR\_0303.pdf**
- **Baseline specifications - diminico\_3ck\_01a\_0319.pdf**
- **MTF - diminico\_3ck\_01\_0519.pdf**

# Overview

Component	802.3cd Insertion Loss dB @ 13.28 GHz	802.3ck Insertion Loss dB @ 26.56 GHz (proposed)	Comment
Module Compliance Board (MCB) PCB	1.2	2.3	
Host Compliance Board (HCB) PCB	1.38	2.5	
Host	7	7	cd-The 7 dB did not include explicit allowances for BGA and connector footprint ck-The 7 dB includes allowance of 1.34 dB for BGA (0.73) via and connector footprint via (0.61)
Host Connector	1.07+0.62	1.6	cd-The host connector is allocated 0.62 dB of additional margin ck- The host connector mating interface is allocated 0.3 dB variation allowance (not including via)
Mated Test Fixture (MTF)	3.65	6.6	
MTF connector	1.07	1.8	ck-includes 0.2 dB via allowance
Bulk cable and wire attachment	12.62	11.8	cd(3m), ck(2m)
Channel	30	29	

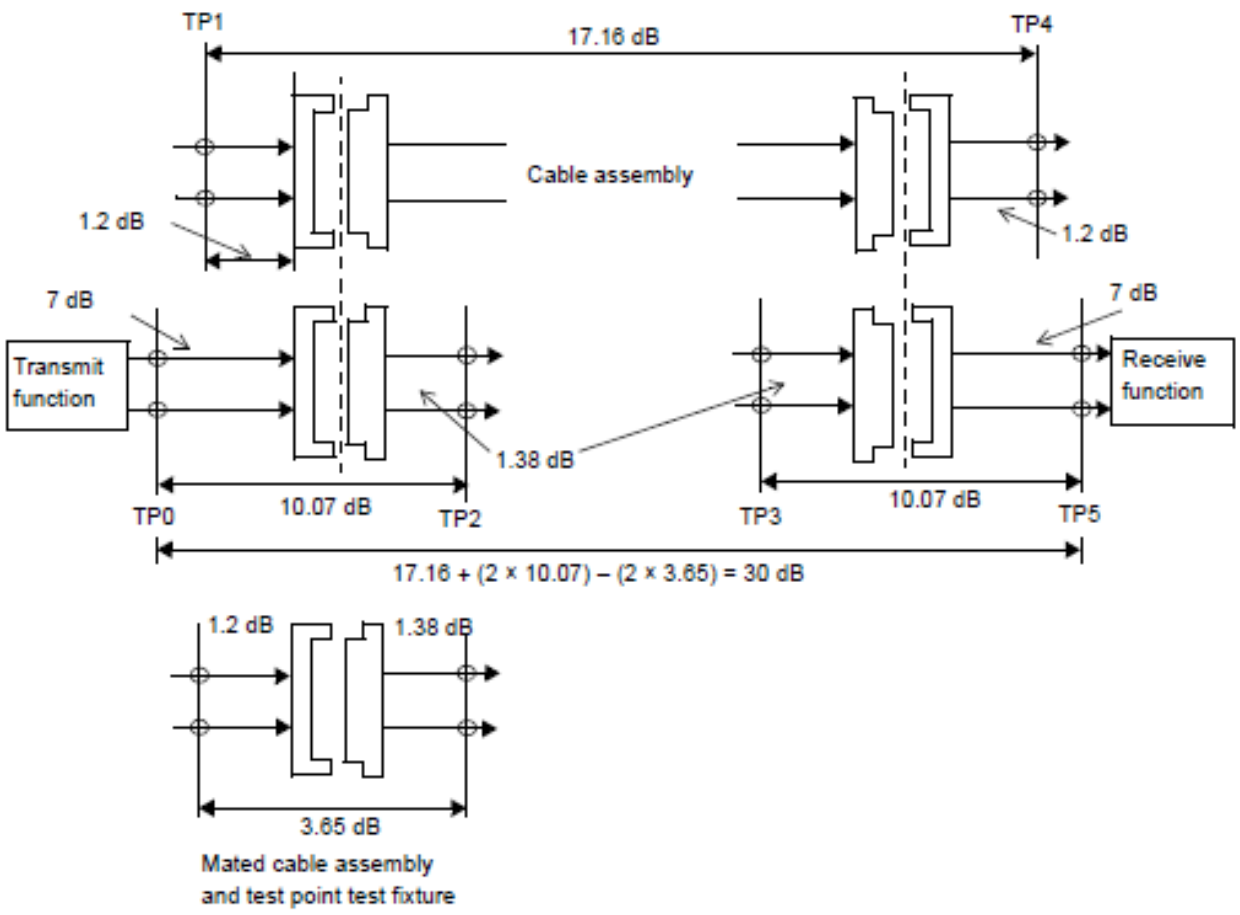
- Host and Mated test fixture connector mating interfaces are the same >>1.3 dB + variation 0.3 dB = 1.6 dB.
- Variation is to account for multiple MDIs and other factors other than implementation or margin.

MTF IL = 2.3(MCB PCB)+1.6(conn)+0.2(via)+2.5(HCB PCB) =6.6 dB

Host Channel IL =7(Host PCB and via's)+1.6(conn)+2.5(HCB PCB) = 11.1 dB

Channel IL =2\*7(Host PCB and via's)+2\*1.6(conn)+11.8(cable and wire termination) = 29 dB

# 802.3cd Figure 136A-1—30 dB channel insertion loss budget at 13.28 GHz

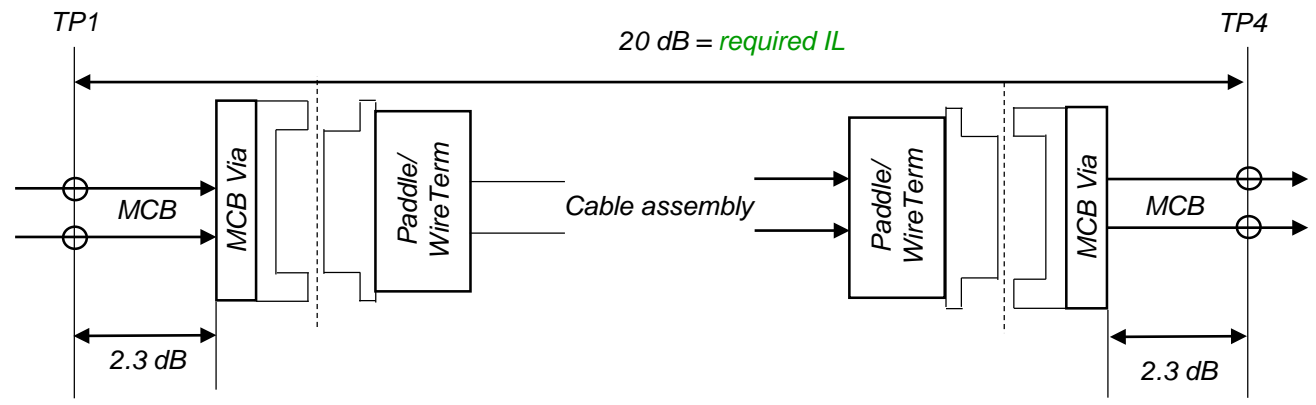


NOTE—The connector insertion loss is 1.07 dB for the mated test fixture. The host connector is allocated 0.62 dB of additional margin.

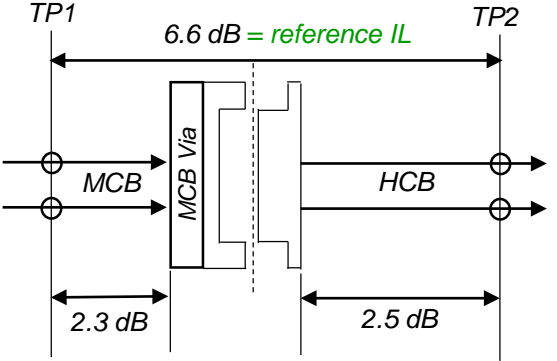
Figure 136A-1—30 dB channel insertion loss budget at 13.28 GHz

# 802.3ck Figure XX-1—29 dB channel insertion loss budget at 26.56 GHz

## Cable Assembly

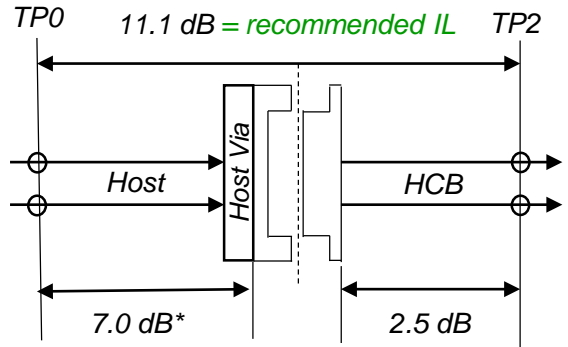


## Mated Test Fixture



Note: 2.3 dB MCB PCB includes test point IL and MCB Via allowance is 0.2 dB

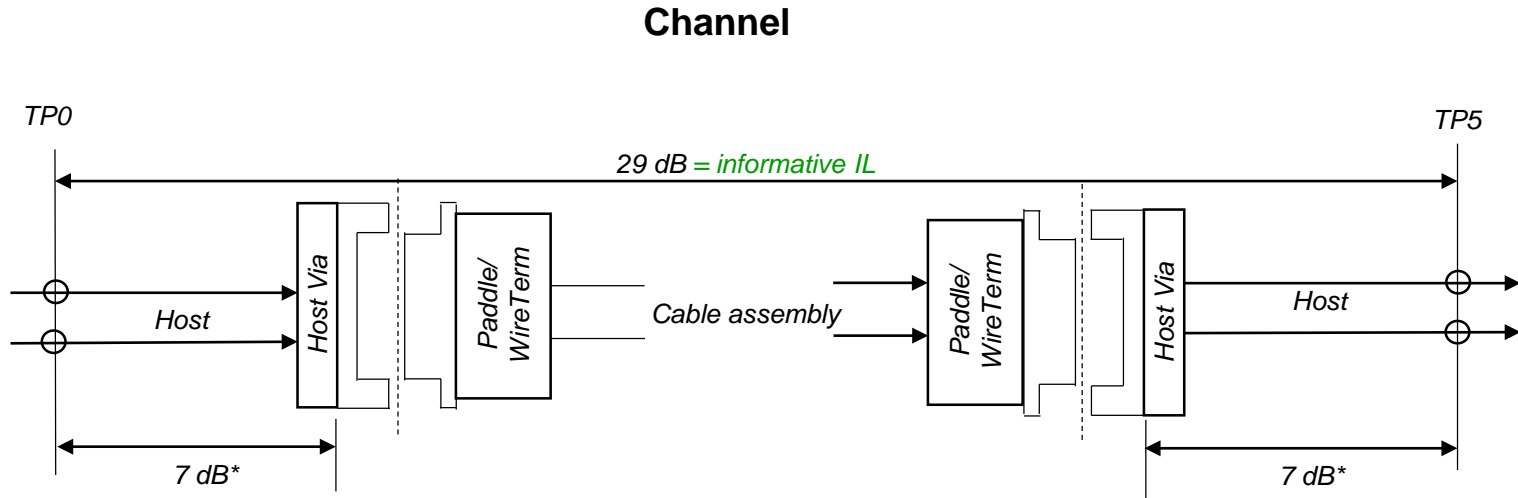
## Host



Note: The 7 dB includes via allowances for BGA and connector footprint



# 802.3ck Figure XX-1—29 dB channel insertion loss budget at 26.56 GHz



**Channel IL = 29 dB @26.56 GHz = 2\*(7+1.6)+11.8**

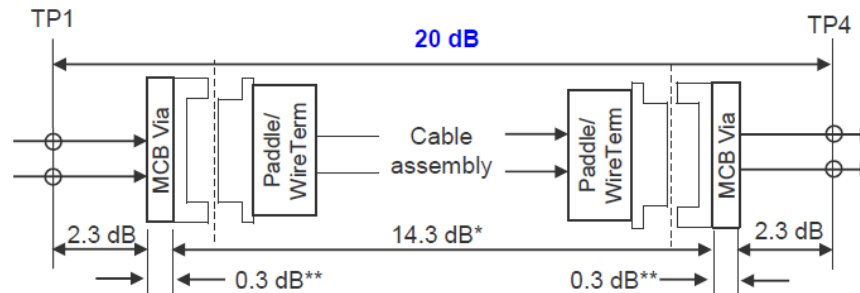
*Note: Channel IL derived from cable assembly host, and mated test fixture IL=29 dB @26.56 GHz = 2\*(7+1.6)+11.8*

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# Supporting Slides

## TP1-TP4 Loss Budget:

- Simulated loss curves put TP1-TP4 loss just below 20 dB
- They are simulated and don't account for manufacturing variation
- Adding some room for error, proposed TP1-TP4 IL: **20 dB**

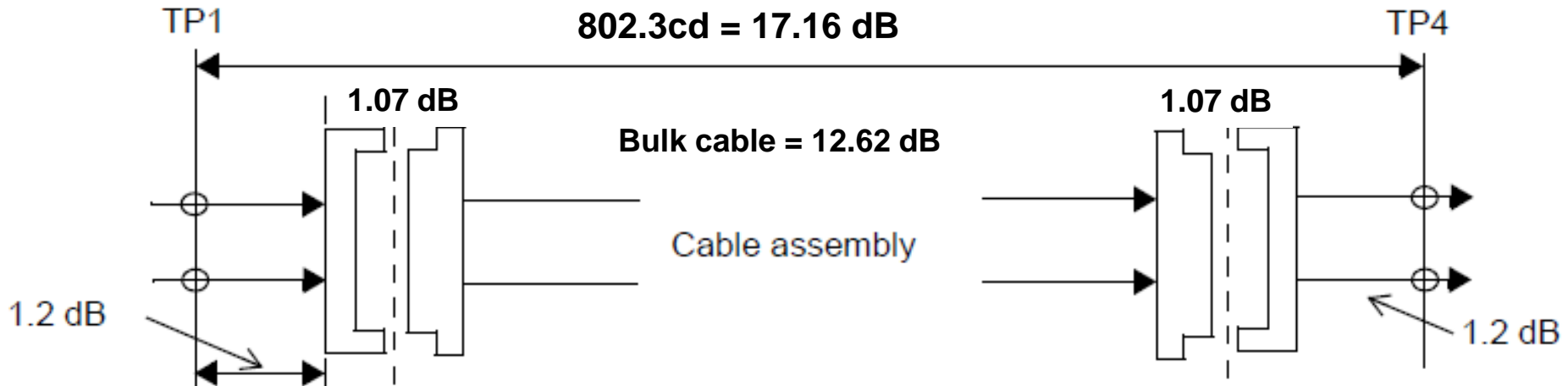


This leaves ~0.5 dB of margin for manufacturing variation

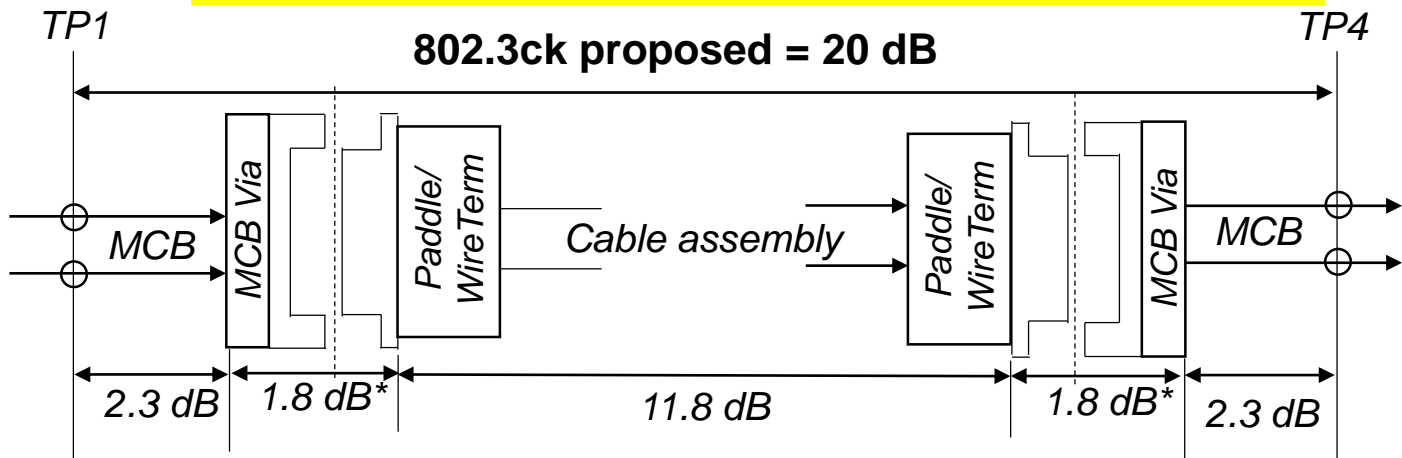
\*Value determined working backwards from 19.5 dB work case loss

\*\*This is a rough estimate based on one MCB design

# Cable assembly - IL Review



**Cable assembly IL= 17.16 dB @13.28 GHz =2\*(1.2+1.07)+12.62**



Note: The connector insertion loss is 1.6 and via allowance of 0.2 dB for the mated test fixture.

**Cable assembly IL =20 dB @26.56 GHz =2\*(2.3+1.6+0.2)+11.8**

# Cable assembly – baseline

- Cable assembly specifications – Adopt CL136 – referenced parameters @ 26.56 GHz,  $f=0.01 \leq f \leq 38$  (signaling rate 53.125 GBd).

## Cable assembly characteristics summary

Parameter description	Value	Unit
Maximum insertion Loss	20	dB
Minimum Insertion Loss	11.15	dB
Minimum ERL	TBD	dB
Differential to Common-mode return loss	Equation(TBD)	dB
Differential to Common-mode conversion loss	Equation(TBD)	dB
Common-mode to common-mode return loss	Equation(TBD)	dB
Minimum COM	TBD	dB

[http://www.ieee802.org/3/ck/public/19\\_03/diminico\\_3ck\\_01\\_0319.pdf](http://www.ieee802.org/3/ck/public/19_03/diminico_3ck_01_0319.pdf)

# Cable Assembly COM- Baseline

- COM - consistent with methodology CL136 – signaling rate 53.125 GBd
- COM parameter values TBD

Table 136–18—COM parameter values

Parameter	Symbol	Value	Units
Signaling rate	$f_b$	26.5625	GBd
Maximum start frequency	$f_{min}$	0.05	GHz
Maximum frequency step <sup>a</sup>	$\Delta f$	0.01	GHz
Device package model			
Single-ended device capacitance	$C_d$	$1.8 \times 10^{-4}$	nF
Transmission line length, Test 1	$z_p$	12	mm
Transmission line length, Test 2	$z_p$	30	mm
Single-ended package capacitance at package-to-board interface	$C_p$	$1.1 \times 10^{-4}$	nF
Package transmission line characteristic impedance	$Z_c$	95	$\Omega$
Single-ended reference resistance	$R_0$	50	$\Omega$

TBD

Table 136–18—COM parameter values (continued)

Parameter	Symbol	Value	Units
Single-ended termination resistance	$R_d$	50	$\Omega$
Receiver 3 dB bandwidth	$f_r$	$0.75 \times f_b$	GHz
Transmitter equalizer, minimum cursor coefficient	$c(0)$	0.6	—
Transmitter equalizer, 1 <sup>st</sup> pre-cursor coefficient	$c(-1)$	—	—
Minimum value		-0.25	
Maximum value		0	
Step size		0.05	
Transmitter equalizer, 2 <sup>nd</sup> pre-cursor coefficient	$c(-2)$	—	—
Minimum value		0	
Maximum value		0.1	
Step size		0.025	
Transmitter equalizer, post-cursor coefficient	$c(1)$	—	—
Minimum value		-0.25	
Maximum value		0	
Step size		0.05	
Continuous time filter, DC gain	$g_{DC}$	—	—
Minimum value		-20	dB
Maximum value		0	dB
Step size		1	dB
Continuous time filter, DC gain 2	$g_{DC2}$	—	—
Minimum value		-6	dB
Maximum value		0	dB
Step size		1	dB
Continuous time filter, zero frequency for $g_{DC} = 0$	$f_z$	$f_b / 2.5$	GHz
Continuous time filter, pole frequencies	$f_{p1}$ $f_{p2}$	$f_b / 2.5$ $2 \times f_b$	GHz GHz
Continuous time filter, low-frequency pole/zero	$f_{LF}$	$f_b / 40$	GHz
Transmitter differential peak output voltage			
Victim	$A_v$	0.415	V
Far-end aggressor	$A_{fb}$	0.415	V
Near-end aggressor	$A_{ne}$	0.604	V
Number of signal levels	$L$	4	—
Level separation mismatch ratio	$R_{LM}$	0.95	—
Transmitter signal-to-noise ratio	$SNR_{TX}$	32.5	dB
Number of samples per unit interval	$M$	32	—
Decision feedback equalizer (DFE) length	$N_b$	12	UI
Normalized DFE coefficient magnitude limit	$b_{max}(n)$	—	—
for $n = 1$		0.7	
for $n = 2$ to $N_b$		0.2	
Random jitter, RMS	$\sigma_{RJ}$	0.01	UI

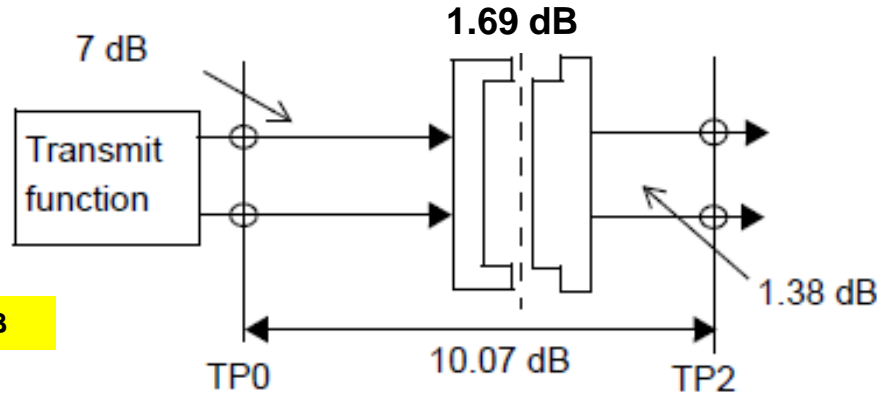
TBD

[http://www.ieee802.org/3/ck/public/19\\_03/diminico\\_3ck\\_01\\_0319.pdf](http://www.ieee802.org/3/ck/public/19_03/diminico_3ck_01_0319.pdf)

## Why 7.0 dB is Required for Host PCB Budget ?

- With Meg-7N material, 4.5mil trace IL at HT is measured to be 1.26 dB/in at 26.56 GHz
- For each front port channel there will be 2 set of vias (at host ASIC BGA footprint & at I/O connector footprint) with stripline routing
  - BGA footprint via with 7.9mil drill is simulated to be 0.73 dB at 26.56 GHz
  - Connector footprint via with 9.8mil drill is simulated to be 0.61 dB at 26.56 GHz
- **Total host PCB budget** =  $(4.5'' \times 1.26 + 0.73 + 0.61) = \underline{\underline{7.01 \text{ dB}}}$
- Revised in this presentation to **Total host loss budget**

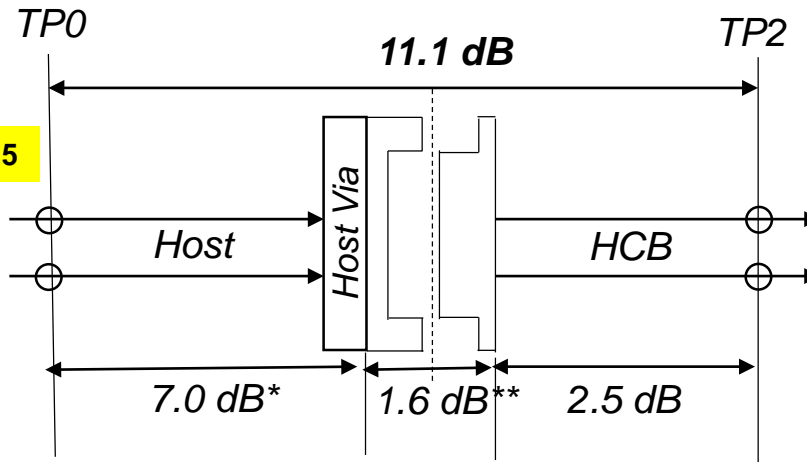
# Host - IL Review



802.3cd

Host IL= 10.07 @13.28 GHz = 7+1.69+1.38 dB

NOTE—The connector insertion loss is 1.07 dB for the mated test fixture. The host connector is allocated 0.62 dB of additional margin.



802.3ck proposed

Host IL = 11.1 dB @26.56 GHz =7.1+1.6+2.5

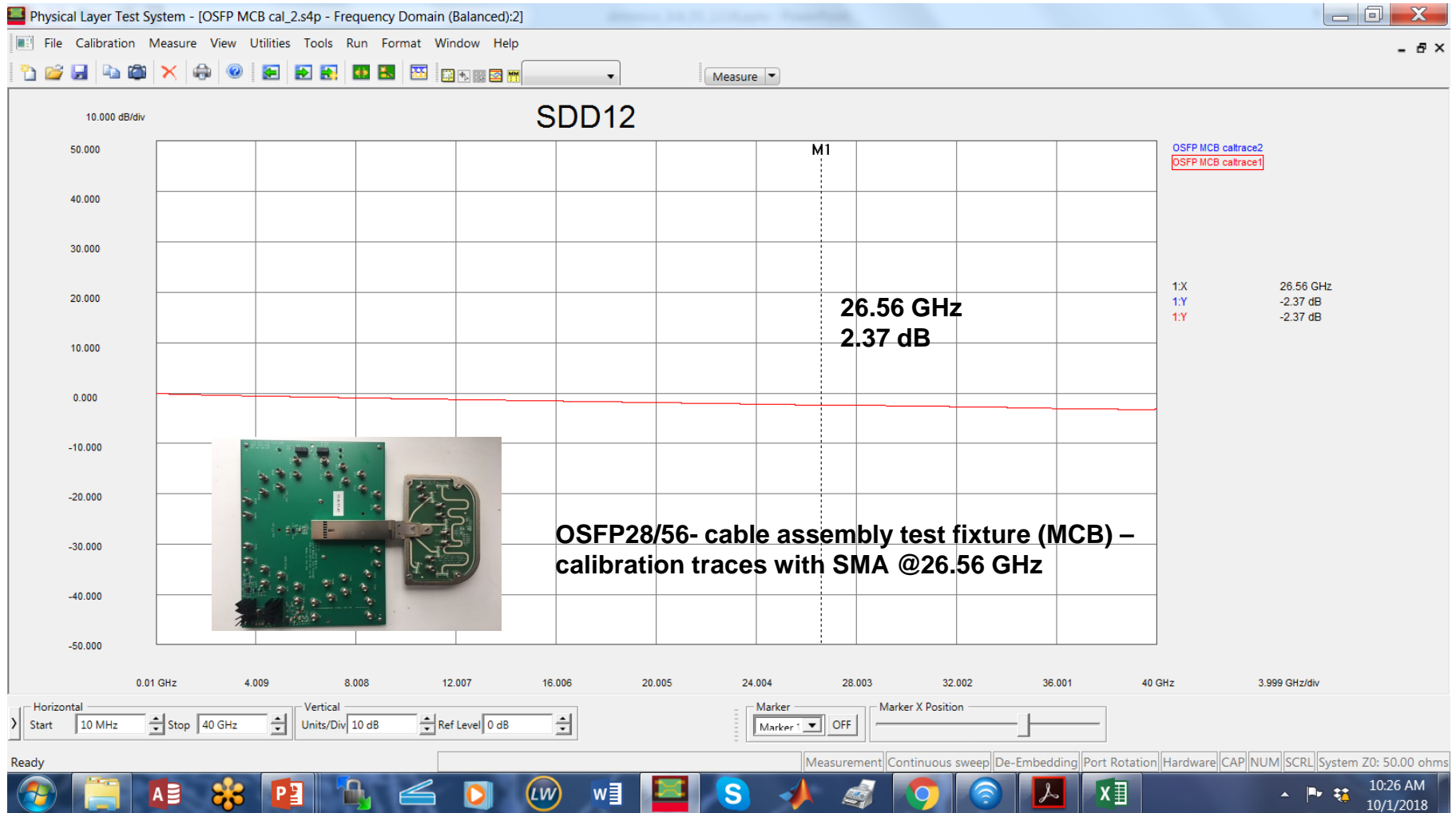
Note: \*The 7 dB includes via allowances of 1.34 dB - BGA (0.73) and connector (0.61).

Note: \*\*The connector mating interface is allocated 0.3 dB implementation allowance.



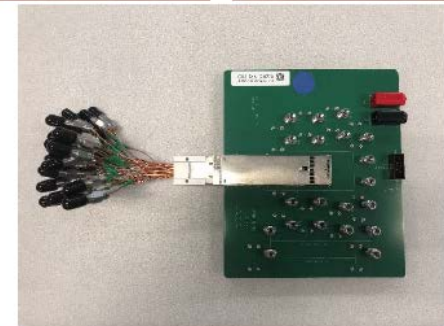
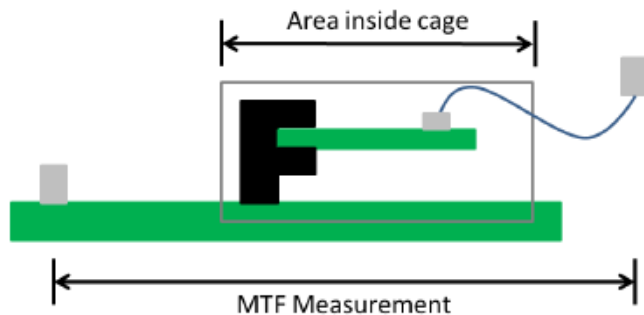
# MTF - diminico\_3ck\_01\_0519.pdf

- MCB reference IL 2.3 dB @ 26.56 GHz achievable with PCB<>SMA



# MTF - diminico\_3ck\_01\_0519.pdf

- PCB + Cable IL 2.5 dB @26.56 GHz Achievable
- Breakout all 16 lanes for QSFP-DD and OSFP testing (32 single ended).
- No de-embedding

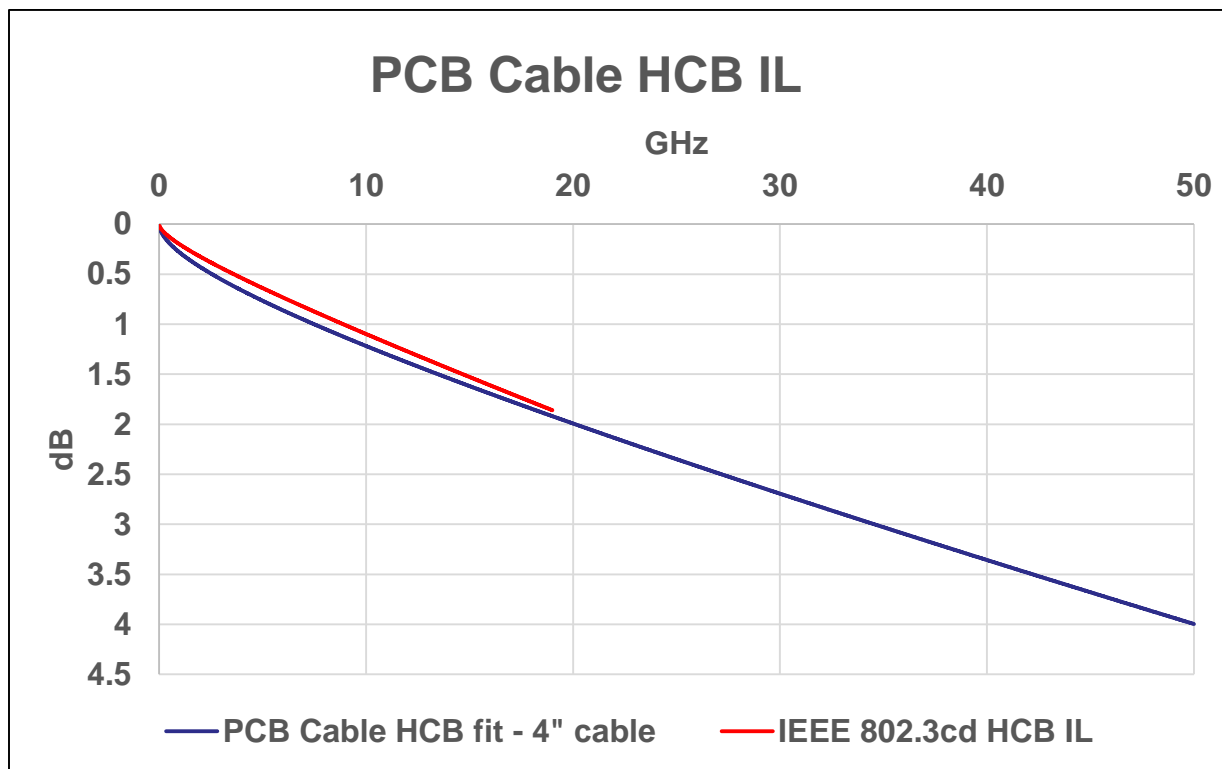


## HCB with PCB and Cable

Content Source: *OIF\_Presentation\_OIF2018\_249\_03.pdf*, Sam Kocsis, Amphenol

# MTF - diminico\_3ck\_01\_0519.pdf

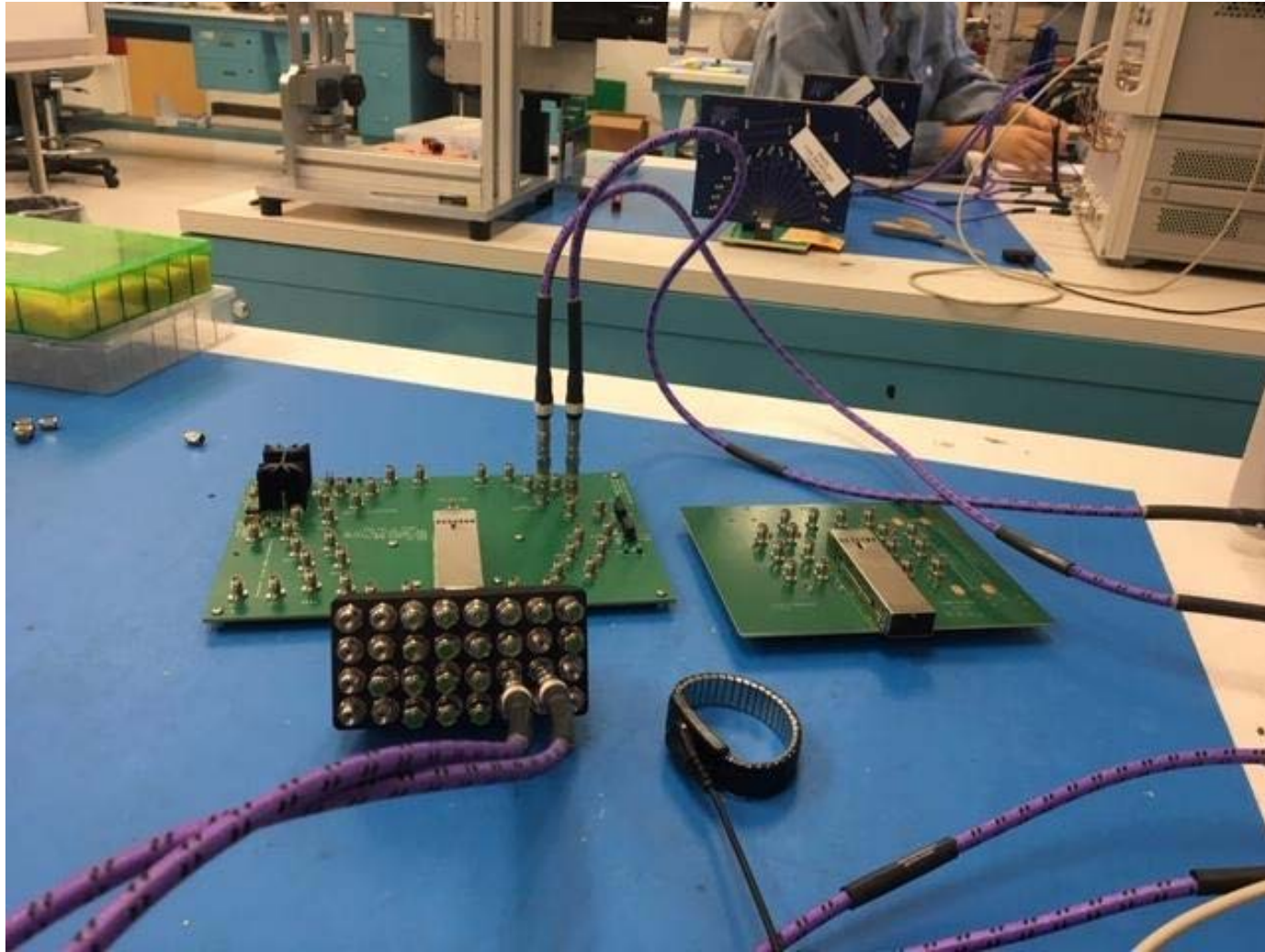
- HCB reference IL 2.5 dB @ 26.56 GHz achievable with PCB Cable HCB



$$HCB\ IL\ (f_{GHz}) = 1.00 * (0.001 + 0.360 * \text{SQRT}(f_{GHz}) - 0.046 * f_{GHz}) \sim 2.5\ \text{dB} \quad 4''\ \text{cable}$$

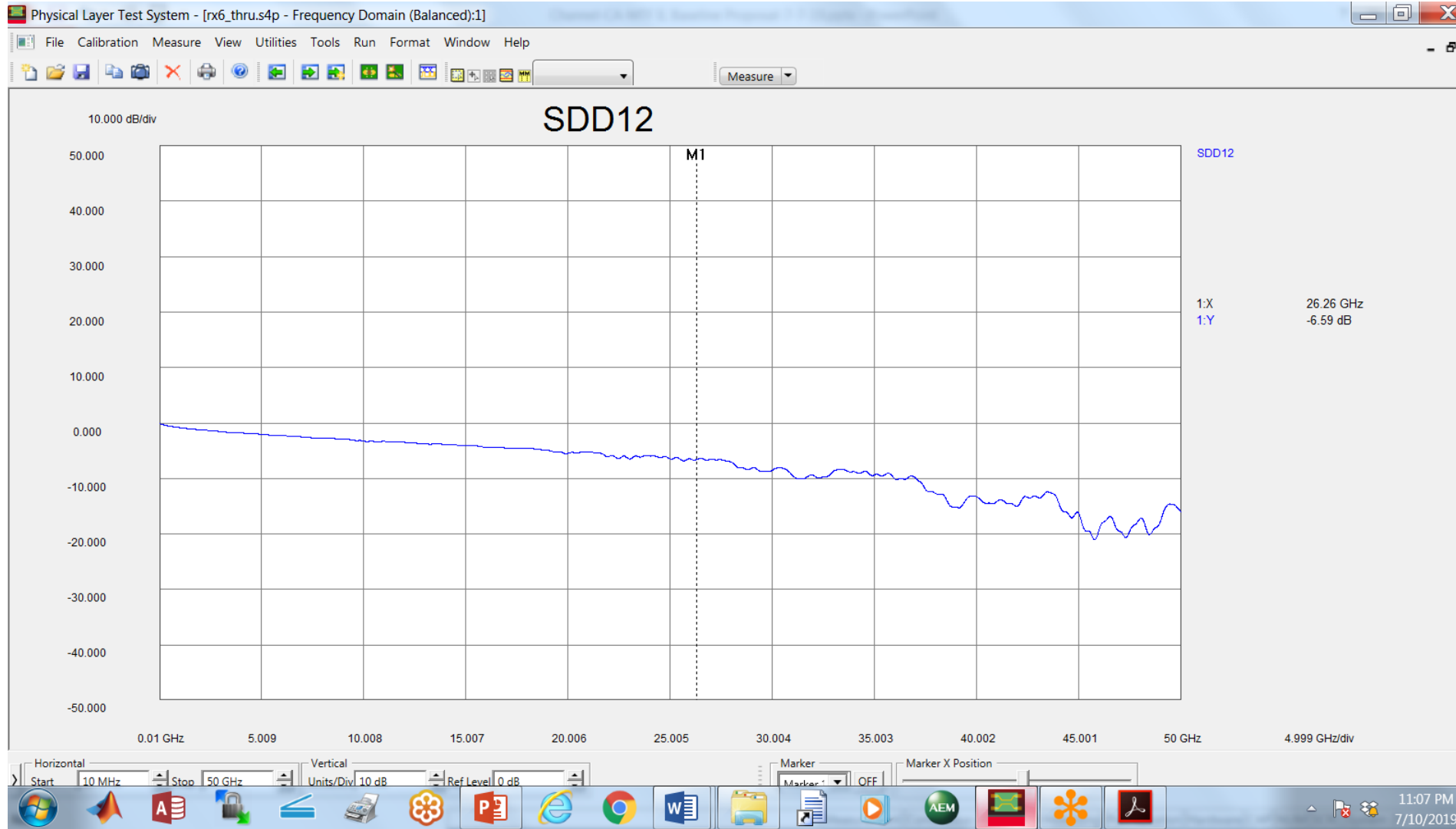
Content Source: OIF\_Presentation\_OIF2018\_249\_03.pdf, Sam Kocsis, Amphenol

# Mated Test Fixtures



*Contributor: Sam Kocsis, Amphenol*

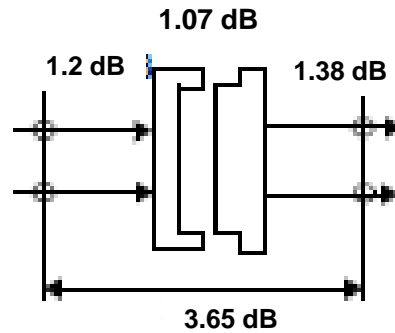
# Mated Test Fixtures - IL



# MTF - IL Review

## 802.3cd

MTF IL= 3.65 @13.28 GHz = 1.2+1.07+1.38 dB



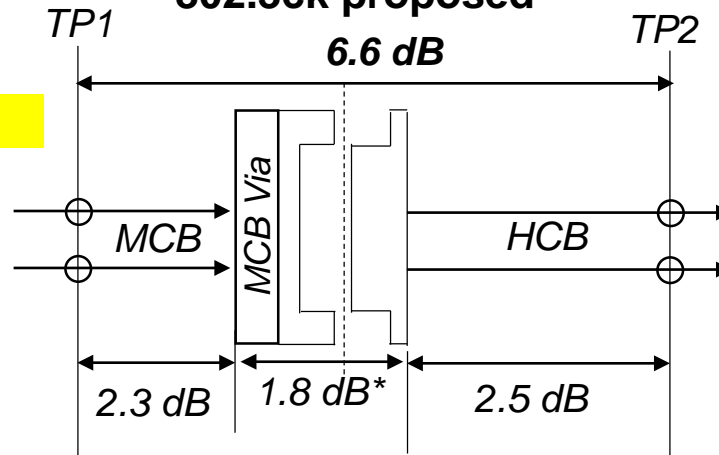
IL @ 13.28 GHz

Mated cable assembly  
and test point test fixture

Note: The connector insertion loss is 1.07 dB for the mated test fixture. The host connector is allocated 0.62 dB of additional margin.

## 802.3ck proposed

MTF IL= 6.6 @26.56 GHz = 2.3+1.8+2.5 dB



Note: includes 0.2 dB via allowance

# 162B.1 Test Fixtures

- 802.3cd
  - (2) groups of MDIs
    - SFP28 MTF (1-Lane MDI)
      - Table 136B-1/2
    - Multi-Lane MTF (2,4,8-Lane MDI)
      - Table 136B-3/4
- 802.3ck
  - (4) groups of MDIs, per palkert\_3ck\_01\_0918
    - SFP112 (1-Lane MDI)
    - SFP112-DD, DSFP (2-Lane MDI)
    - QSFP112, microQSFP, (4-Lane MDI)
    - QSFP-DD, OSFP (8-Lane MDI)

[http://www.ieee802.org/3/ck/public/18\\_09/palkert\\_3ck\\_01\\_0918.pdf](http://www.ieee802.org/3/ck/public/18_09/palkert_3ck_01_0918.pdf)

# 162B.1.1.1 MTF Insertion Loss

- Update MCB and HCB IL requirements, per diminico\_3ck\_01\_0519
  - IL (CATF/MCB) =  $1.073*(-0.00125+0.12*\sqrt{f}+0.0575*f) = 2.3\text{dB}$  (26.56GHz)
  - IL (HCB) =  $1.00*(0.001+0.360*\sqrt{f}-0.046*f) = 2.5\text{dB}$  (26.56GHz)

[http://www.ieee802.org/3/ck/public/19\\_05/diminico\\_3ck\\_01\\_0519.pdf](http://www.ieee802.org/3/ck/public/19_05/diminico_3ck_01_0519.pdf)

- Update reference insertion loss equation 136B-1,

The reference insertion loss of the mated test fixture is determined using Equation (136B-1).

$$IL_{\text{MatedTF}}(f) = 0.471\sqrt{f} + 0.1194f + 0.002f^2 \text{ (dB)} \quad (136B-1)$$

for  $0.01 \text{ GHz} \leq f \leq 25 \text{ GHz}$

where

$f$  is the frequency in GHz

$$\begin{aligned} IL_{\text{matedTF}}(f) &= 0.9502*(0.471*\text{SQRT}(f)+0.1194*f+0.002*f^2) \\ &= 6.6 \text{ @26.56 GHz} \end{aligned}$$



# Table 136B-1 and 136B-3 – MTF (ICN) Tables

Table 136B-1—SFP28 mated test fixture integrated near-end crosstalk noise parameters

Description	Symbol	Value	Units
Symbol rate	$f_b$	26.5625	GBd
3 dB reference receiver bandwidth	$f_r$	19.92	GHz
Near-end disturber peak differential output amplitude	$A_{nt}$	600	mV
Near-end disturber 20% to 80% rise and fall times	$T_{nt}$	9.27	ps

Table 136B-3—Multi-lane mated test fixture integrated crosstalk noise parameters

Description	Symbol	Value	Units
Symbol rate	$f_b$	26.5625	GBd
3 dB reference receiver bandwidth	$f_r$	19.92	GHz
Near-end disturber peak differential output amplitude	$A_{nt}$	600	mV
Far-end disturber peak differential output amplitude	$A_{ft}$	600	mV
Near-end disturber 20% to 80% rise and fall times	$T_{nt}$	9.27	ps
Far-end disturber 20% to 80% rise and fall times	$T_{ft}$	9.27	ps

# 162B.1.1.6 Mated test fixtures (ICN) Tables

Description	Symbol	Value	Units
Symbol rate	$f_b$	53.125	GBd
3dB reference receiver bandwidth	$f_r$	39.84	GHz
Near-end disturber peak differential output amplitude	$A_{nt}$	600	mV
Far-end disturber peak differential output amplitude	$A_{ft}$	600	mV
Near-end disturber 20% to 80% rise and fall times	$T_{nt}$	TBD	ps
Far-end disturber 20% to 80% rise and fall times	$T_{ft}$	TBD	ps

# 162B.1.1 Mated test fixtures

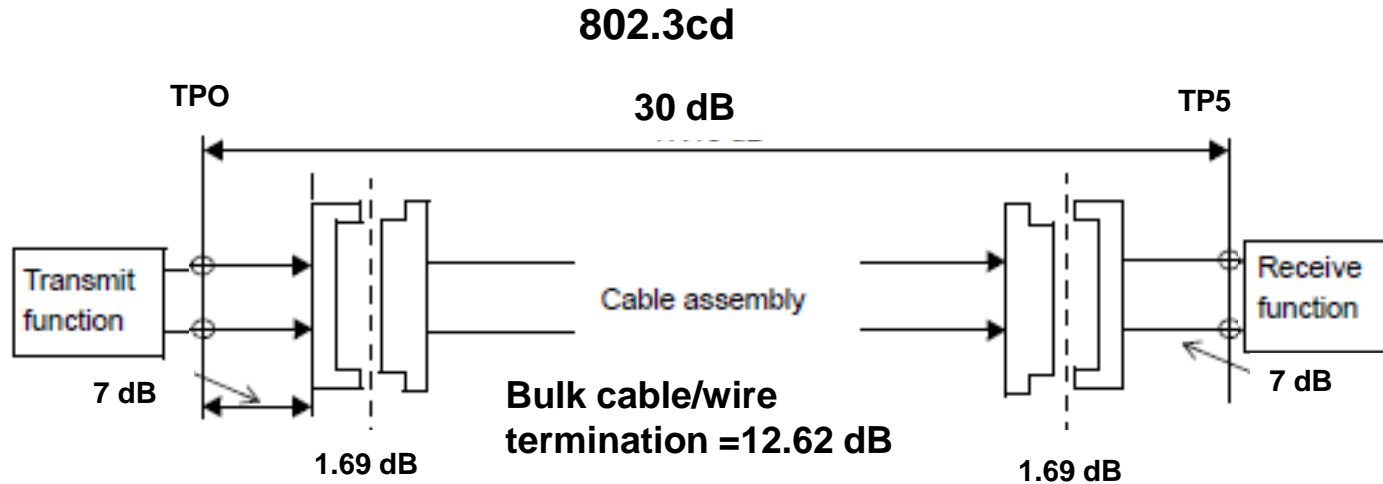
- Test Fixture specifications – Adopt– referenced parameters 26.56 GHz  $f=0.01 \leq f \leq 40$  (signaling rate 53.125 GBd).

## Mated test fixtures parameters

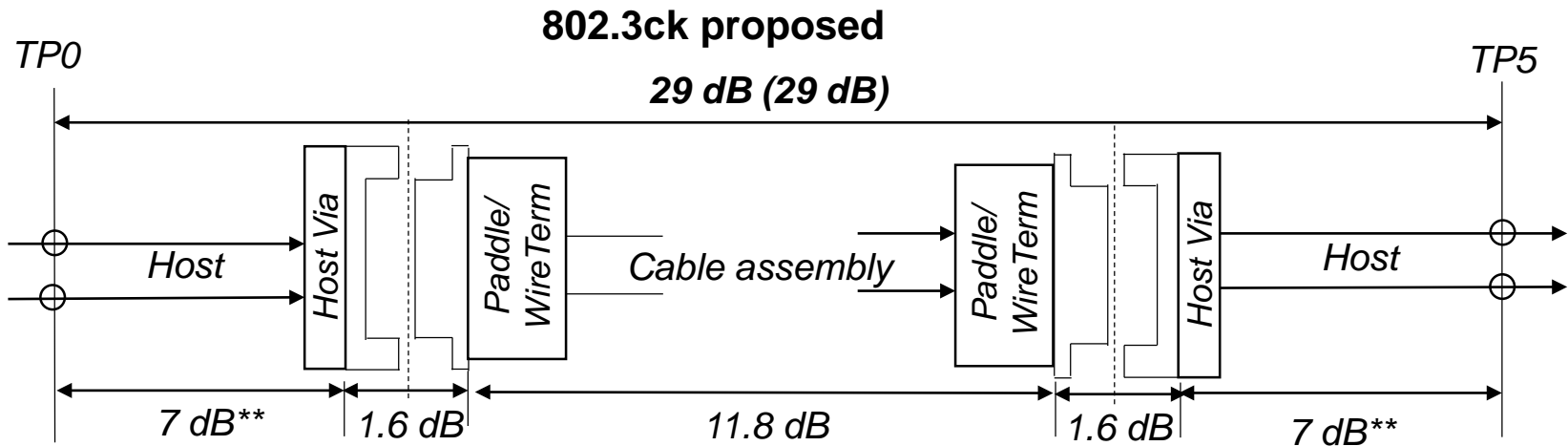
Parameter description	Value	Unit
Maximum differential insertion Loss	Equation(TBD)	dB
Minimum differential Insertion Loss	Equation(TBD)	dB
Reference differential insertion loss	Equation (slide 22)	dB
Figure of Merit(FOM) ILD	Equation(TBD)	dB
Minimum Differential Return Loss	Equation(TBD)	dB
Common-mode conversion insertion loss	Equation(TBD)	dB
Common-mode return loss	Equation(TBD)	dB
Common-mode to differential –mode return loss	Equation(TBD)	dB
Integrated crosstalk noise	(TBD)	mV

[http://www.ieee802.org/3/ck/public/19\\_03/diminico\\_3ck\\_01\\_0319.pdf](http://www.ieee802.org/3/ck/public/19_03/diminico_3ck_01_0319.pdf)

# Channel - IL Review



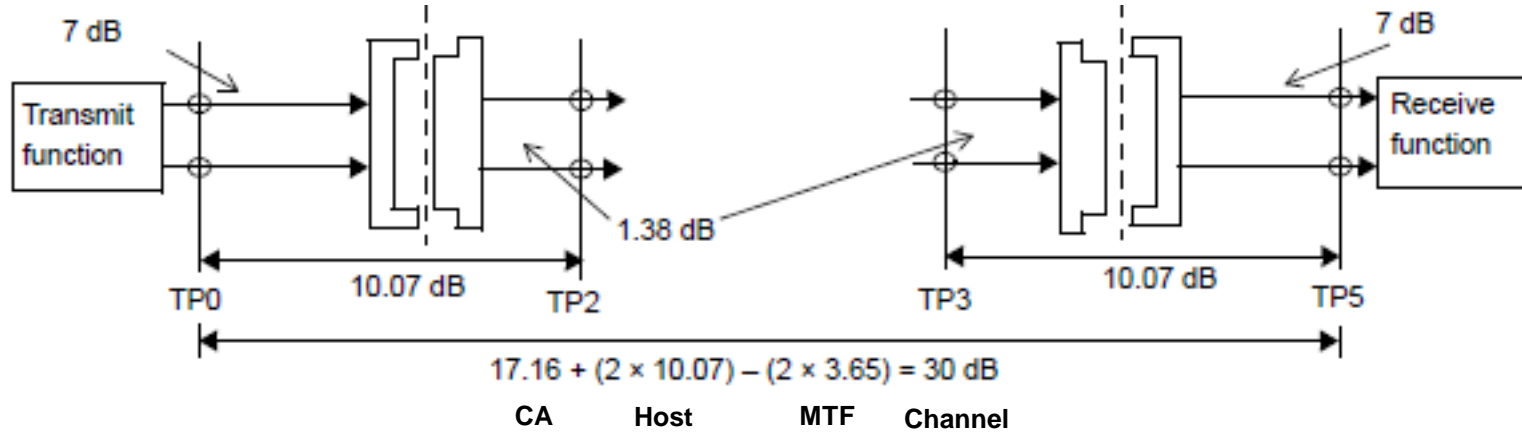
**Channel IL = 30 dB @13.28 GHz = 2\*(7+1.69)+12.62**



**Channel IL (TBD) = 29 dB @26.56 GHz = 2\*(7+1.6)+11.8**

# Channel - IL Review

## 802.3cd



## 802.3ck proposed

